Fluxgate Based Displacement Sensor

Project Title:

Designed for:

Public Release

Assembly Variant:

001

Label Table

<table>
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<tr>
<th>Variant</th>
<th>Label Text</th>
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<td>VREF=VDD/2</td>
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Assembly Note

ZZ1

PCB Label

Size: 0.65" x 0.20"

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2

PCB Label

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

PCB Label

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

PCB Label

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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